


Date: 4/25/2021

Material Number: EFR32BG12P132F1024GM48-C

Pkg Config.: PK1572

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	58.80	Carbon Black	1333-86-4	0.400	0.235	4000	0.1711	1711
			Epoxy Resin (Proprietary)	Proprietary	7.000	4.116	70000	2.9938	29938
			Metal Hydroxide	Proprietary	2.000	1.176	20000	0.8554	8554
			Phenol Resin (Proprietary)	Proprietary	5.000	2.940	50000	2.1384	21384
			Silica (Amorphous) B	60676-86-0	85.600	50.333	856000	36.6097	366097
2	Plating - External	4.20	Tin	7440-31-5	100.000	4.200	1000000	3.0549	30549
3	Bond Wire	0.35	Copper	7440-50-8	96.550	0.334	965500	0.2430	2430
			Gold	7440-57-5	0.350	0.001	3500	0.0009	9
			Palladium	7440-05-3	3.100	0.011	31000	0.0078	78
4	Die Attach Epoxy	1.90	Copper	7440-50-8	10.000	0.190	100000	0.1382	1382
			Hardener (Proprietary)	Proprietary	2.000	0.038	20000	0.0276	276
			Liquid Rubber	Proprietary	12.500	0.238	125000	0.1727	1727
			Mixed Diluents	Proprietary	6.500	0.124	65000	0.0898	898
			Modified Epoxy Resins	Proprietary	1.500	0.028	15000	0.0207	207
			Silver	7440-22-4	67.500	1.282	675000	0.9328	9328
5	Leadframe	65.30	Chromium	7440-47-3	0.250	0.163	2500	0.1187	1187
			Copper	7440-50-8	99.280	64.830	992800	47.1541	471541
			Tin	7440-31-5	0.250	0.163	2500	0.1187	1187
			Zinc	7440-66-6	0.220	0.144	2200	0.1045	1045
6	Plating - Internal	1.30	Silver	7440-22-4	100.000	1.300	1000000	0.9456	9456
7	Die	5.64	Silicon	7440-21-3	99.800	5.628	998000	4.0933	40933
			Silicon Dioxide	60676-86-0	0.200	0.011	2000	0.0082	82
	Total Unit Weight =	137.49				137.49		100.0000	1000000